



Attorney Docket No.: PATENT
SSI-04001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

William Dale Jones

Serial No.: 10/680,783

Filed: October 6, 2003

For: **HIGH-PRESSURE CHAMBER FOR
A SEMICONDUCTOR WAFER**

) Group Art Unit: 1765

) Examiner:

) **INFORMATION DISCLOSURE**
) **STATEMENT**

) 162 N. Wolfe Road
) Sunnyvale, CA 94086
) (408) 530-9700

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #53495); (EFS ID #53497); (EFS ID #53498); and (EFS ID #53499). Applicants have become aware of the following printed publication which may be material to the examination of this application:

- Chinese Publication No. CN 1399790 A;
- German Publication No. DE 36 08 783 A1;
- German Publication No. DE 198 60 084 A1;
- European Publication No. EP 0 244 951 A2;
- European Publication No. EP 0 272 141 A2;
- European Publication No. EP 0 453 867 A1;
- European Publication No. EP 0 572 913 A1;
- European Publication No. EP 0 587 168 A1;
- European Publication No. EP 0 679 753 B1;
- European Publication No. EP 0 903 775 A2;
- French Publication No. FR 1 499 491;

- Great Britain Publication No. GB 2 003 975;
- Great Britain Publication No. GB 2 193 482;
- Japanese Patent Abstract JP 2-148841;
- Japanese Patent Abstract JP 2-209729;
- Japanese Patent Abstract JP 8-186140;
- Japanese Patent Abstract JP 10-144757;
- Japanese Patent Abstract JP 10-335408;
- Japanese Patent Abstract JP 11-200035;
- Japanese Patent Abstract JP 56-142629;
- Japanese Patent Abstract JP 60-238479;
- Japanese Patent Abstract JP 60-246635;
- Japanese Patent Abstract JP 61-231166;
- Japanese Patent Abstract JP 62-125619;
- Japanese Patent Abstract JP 63-303059;
- Japanese Patent Abstract JP 2000/106358;
- Swiss Publication No. SE 251213;
- PCT Publication No. WO 87/07309;
- PCT Publication No. WO 91/12629;
- PCT Publication No. WO 99/18603;
- PCT Publication No. WO 00/36635;
- PCT Publication No. WO 01/10733 A1;
- PCT Publication No. WO 01/33615 A3;
- PCT Publication No. WO 01/55628 A1;
- PCT Publication No. WO 01/68279 A2;
- PCT Publication No. WO 01/74538 A1;
- PCT Publication No. WO 01/78911 A1;
- PCT Publication No. WO 01/85391 A2;
- PCT Publication No. WO 01/94782 A3;
- PCT Publication No. WO 02/16051 A2;
- PCT Publication No. WO 03/030219 A2;
- Hideaki Itakura et al., "Multi-Chamber Dry Etching System", Solid State Technology, April 1982, pp. 209-214;


- Sun, Y.P. et al., "Preparation of Polymer-Protected Semiconductor Nanoparticles Through the Rapid Expansion of Supercritical Fluid Solution," Chemical Physics Letters, pp. 585-588, May 22, 1998;
- Dahmen, N. et al., "Supercritical Fluid Extraction of Grinding and Metal Cutting Waste Contaminated with Oils," Supercritical Fluids - Extraction and Pollution Prevention, ACS Symposium Series, Vol. 670, pp. 270-279, 21 Oct 1997;
 - Xu, C. et al., "Submicron-Sized Spherical Yttrium Oxide Based Phosphors Prepared by Supercritical CO₂-Assisted aerosolization and pyrolysis," Appl. Phys. Lett., Vol. 71, No.12, September 22, 1997, pp. 1643-1645;
 - Courtecuisse, V.G. et al., "Kinetics of the Titanium Isopropoxide Decomposition in Supercritical Isopropyl Alcohol," Ind. Eng. Chem. Res., Vol. 35, No. 8, pp. 2539-2545, Aug 1996;
 - Gallagher-Wetmore, P. et al., "Supercritical Fluid Processing: A New Dry Technique for Photoresist Developing," SPIE Vol. 2438, pp.694-708, Jun. 1995.
 - McHardy, J. et al., "Progress in Supercritical CO₂ Cleaning," SAMPE Jour., Vol. 29, No. 5, pp. 20-27, September 1993;
 - Purtell, R. et al., "Precision Parts Cleaning using Supercritical Fluids," J. Vac, Sci, Technol. A. Vol. 11, No. 4, July 1993, pp. 1696-1701;
 - Hansen, B.N. et al., "Supercritical Fluid Transport - Chemical Deposition of Films," Chem. Mater., Vol. 4, No. 4, pp, 749-752, 1992;
 - Hybertson, B.M. et al., "Deposition of Palladium Films by a Novel Supercritical Fluid Transport Chemical Deposition Process," Mat. Res. Bull., Vol. 26, pp. 1127-1133, 1991;
 - Ziger, D. H. et al., "Compressed Fluid Technology: Application to RIE-Developed Resists," AiChE Jour., Vol. 33, No. 10, pp. 1585- 1591, October 1987;
 - Matson, D.W. et al., "Rapid Expansion of Supercritical Fluid Solutions: Solute Formation of Powders, Thin Films, and Fibers," Ind. Eng. Chem. Res., Vol. 26, No. 11, pp. 2298-2306, 1987;
 - Tolley, W.K. et al., "Stripping Organics from Metal and Mineral Surfaces using Supercritical Fluids," Separation Science and Technology, Vol. 22, pp. 1087-1101, 1987;
 - Joseph L. Foszcz, "Diaphragm Pumps Eliminate Seal Problems", Plant Engineering , pp. 1-5, February 1, 1996; and

- Bob Agnew, "WILDEN Air-Operated Diaphragm Pumps", Process & Industrial Training Technologies, Inc., 1996.

This Information Disclosure Statement under 37 C.F.R. §§ 1.56 and 1.97 is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that anyone or more of these citations constitutes prior art.

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 1-12-04

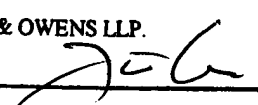
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Thomas B. Haverstock
Reg. No.: 32,571

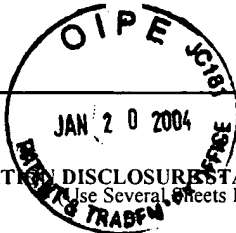
Attorneys for Applicant

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- 4 -

HAVERSTOCK & OWENS LLP.
Date: 1-12-04 By: 

FORM PTO-1449
(Modified)U.S. Department of Commerce
Patent and Trademark Office

Attorney Docket No.: SSI-04001

Serial No.: 10/680,783

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use Several Sheets If Necessary)

Applicant: William Dale Jones

Filing Date: October 6, 2003

Group Art Unit: 1765

(37 CFR § 1.98(b))

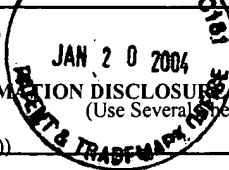
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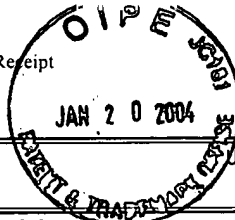
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Examiner:

Date Considered:

EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)				Filing Date: October 6, 2003	Group Art Unit: 1765			
(37 CFR § 1.98(h))								
FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS								
		Document Number	Publication Date	Country / Patent Office	Class	Subclass	Translation	
							Yes	No
	BJ	WO 01/74538 A1	10/11/01	PCT	B24C	1/00		X
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	BM	WO 01/94782 A3	12/13/01	PCT	F04B	43/02		X
	BN	WO 02/16051 A2	02/28/02	PCT	B05D			X
	BO	WO 03/030219 A2	10/04/03	PCT	H01L			X
OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)								
	BP	Hideaki Itakura et al., "Multi-Chamber Dry Etching System", Solid State Technology, April 1982, pp. 209-214.						
	BQ	Sun, Y.P. et al., "Preparation of Polymer-Protected Semiconductor Nanoparticles Through the Rapid Expansion of Supercritical Fluid Solution," Chemical Physics Letters, pp. 585-588, May 22, 1998.						
	BR	Dahmen, N. et al., "Supercritical Fluid Extraction of Grinding and Metal Cutting Waste Contaminated with Oils," Supercritical Fluids - Extraction and Pollution Prevention, ACS Symposium Series, Vol. 670, pp. 270-279, 21 Oct 1997.						
	BS	Xu, C. et al., "Submicron-Sized Spherical Yttrium Oxide Based Phosphors Prepared by Supercritical CO ₂ -Assisted aerosolization and pyrolysis," Appl. Phys. Lett., Vol. 71, No.12, September 22, 1997, pp. 1643-1645.						
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	BU	Gallagher-Wetmore, P. et al., "Supercritical Fluid Processing: A New Dry Technique for Photoresist Developing," SPIE Vol. 2438, pp.694-708, Jun. 1995.						
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	BX	Hansen, B.N. et al., "Supercritical Fluid Transport - Chemical Deposition of Films," Chem. Mater., Vol. 4, No. 4, pp. 749-752, 1992.						
	BY	Hybertson, B.M. et al., "Deposition of Palladium Films by a Novel Supercritical Fluid Transport Chemical Deposition Process," Mat. Res. Bull., Vol. 26, pp. 1127-1133, 1991.						
	BZ	Ziger, D. H. et al., "Compressed Fluid Technology: Application to RIE-Developed Resists," AiChE Jour., Vol. 33, No. 10, pp. 1585- 1591, October 1987.						
	CA	Matson, D.W. et al., "Rapid Expansion of Supercritical Fluid Solutions: Solute Formation of Powders, Thin Films, and Fibers," Ind. Eng. Chem. Res., Vol. 26, No. 11, pp. 2298-2306, 1987.						
	CB	Tolley, W.K. et al., "Stripping Organics from Metal and Mineral Surfaces using Supercritical Fluids," Separation Science and Technology, Vol. 22, pp. 1087-1101, 1987.						
	CC	Joseph L. Foszcz, "Diaphragm Pumps Eliminate Seal Problems", Plant Engineering , pp. 1-5, February 1, 1996.						
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Examiner:				Date Considered:				
EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								



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ACKNOWLEDGEMENT RECEIPT

Electronic Version 1.1

Stylesheet Version v1.1.1

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER									
Submission Type:	Information Disclosure Statement									
Application Number:	10/680783	*10/680783*								
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Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER		
Application Number:	10/680783	*10/680783*	
Date:	2003-10-06		
First Named Applicant:	William Dale Jones		
Confirmation Number:	5859		
Attorney Docket Number:			
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Thomas B. Haverstock		/tbh/	Attorney
Registered Number: 32571			

Documents being submitted	Files
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Title of
InventionHIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR
WAFER

Application Number: 10/680783 *10/680783*
Confirmation Number: 5859
First Named Applicant: William Jones
Attorney Docket Number:
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US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6521466	2002-02-18	Castrucci	B1		
	2	6541278	2003-04-01	Morita et al.	B1		
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	4	6550484	2003-04-22	Gopinath et al.	B1		
	5	6558475	2003-05-06	Jur et al.	B1		
	6	6561213	2003-05-13	Wang et al.	B1		
	7	6561220	2003-05-13	McCullough et al.	B1		
	8	6561481	2003-05-13	Filonczuk	B1		
	9	6561767	2003-05-13	Biberger et al.	B1		
	10	6564826	2003-05-20	Shen	B1		
	11	5217043	1993-06-08	Novakovi			

US Published Applications

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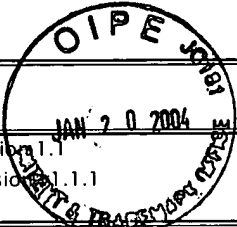
Remarks

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Non US Patent and Publication references shall be filed under a separate paper transmittal.
The current electronic filing contains part 4 out of a total of 4 electronic filings.

Signature

Examiner Name	Date

	
UNITED STATES PATENT AND TRADEMARK OFFICE ACKNOWLEDGEMENT RECEIPT	
Electronic Version 1.1 Stylesheet Version 1.1.1	

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER										
Submission Type:	Information Disclosure Statement										
Application Number:	10/680783	*10/680783*									
EFS ID:	53495										
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Application Number:	10/680783 *10/680783*						
Date:	2003-10-06						
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First Named Applicant:	William Jones						
Attorney Docket Number:							
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
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	1	2617719	1952-11-11	C. R. Stewart			
	2	2625886	1953-01-20	Browne			
	3	3744660	1973-07-10	Gaines et al.			
	4	3968885	1976-07-13	Hassan et al.			
	5	4029517	1977-06-14	Rand			
	6	4091643	1978-05-30	Zucchini			
	7	4245154	1981-01-13	Uehara et al.			

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8	4341592	1982-07-27	Shortes et al.
9	4355937	1982-10-26	Mack et al.
10	4367140	1983-01-04	Wilson
11	4406596	1983-09-27	Budde
12	4422651	1983-12-27	Platts
13	4474199	1984-10-02	Blaudszun
14	4522788	1995-06-11	Sitek et al.
15	4549467	1985-10-29	Wilden et al.
16	4592306	1986-06-03	Callego
17	4601181	1986-07-22	Privat
18	4626509	1986-12-02	Lyman
19	4670126	1987-06-02	Messer et al.
20	4682937	1987-07-28	Credle, Jr.
21	4693777	1987-09-15	Hazano et al.
22	4749440	1988-06-07	Blackwood et al.
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24	4788043	1988-11-29	Kagiyama et al.
25	4789077	1988-12-06	Noe
26	4823976	1989-04-25	White, III et al.
27	4825808	1989-05-02	Takahashi et al.
28	4827867	1989-05-09	Takei et al.
29	4838476	1989-06-13	Rahn
30	4865061	1989-09-12	Fowler et al.
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32	4917556	1990-04-17	Stark et al.
33	4924892	1990-05-15	Kiba et al.
34	4951601	1990-08-28	Maydan et al.
35	4960140	1990-10-02	Ishijima et al.
36	4983223	1991-01-08	Gessner
37	5011542	1991-04-30	Weil
38	5044871	1991-09-03	Davis et al.
39	5062770	1991-11-05	Story et al.

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	40	5071485	1991-12-10	Matthews et al.			
	41	5105556	1992-04-21	Kurokawa et al.			
	42	5143103	1992-09-01	Basso et al.			
	43	5167716	1992-12-01	Boltnott et al.			
	44	5169296	1992-12-08	Wilden			
	45	5169408	1992-12-08	Biggerstaff et al.			
	46	5185296	1993-02-09	Morita et al.			
	47	5186718	1993-02-16	Tepman et al.			
	48	5188515	1993-02-23	Horn			
	49	5190373	1993-03-02	Dickson et al.			
	50	5191993	1993-03-09	Wanger et al.			

Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal.
The current electronic filing contains part 1 out of a total of 4 electronic filings.

Signature

Examiner Name	Date

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1/12/2004

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ACKNOWLEDGEMENT RECEIPT**

Electronic Version 1.1
Stylesheet Version v1.1.1

Title of Invention

HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER

Submission Type: Information Disclosure Statement

Application Number: 10/680783

10/680783

EFS ID: 53497

Server Response:

Confirmation Code	Message
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First Named Applicant: William Jones

Attorney Docket Number:

Timestamp: 2004-01-12 14:22:14 EDT

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Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER		
Application Number:	10/680783	*10/680783*	
Date:	2003-10-06		
First Named Applicant:	William Dale Jones		
Confirmation Number:	5859		
Attorney Docket Number:			
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>			
Submitted by:		Elec. Sign.	Sign. Capacity
Thomas B. Haverstock Registered Number: 32571		/tbh/	Attorney

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Stylesheet Version v18.0

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Confirmation Number:	5859						
First Named Applicant:	William Jones						
Attorney Docket Number:							
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	1	5193560	1993-03-16	Tanaka et al.			
	2	5195878	1993-03-23	Sahlavo et al.			
	3	5213485	1993-05-25	Wilden			
	4	5221019	1993-06-22	Pechacek			
	5	5222876	1993-06-29	Budde			
	6	5224504	1993-07-06	Thompson et al.			
	7	5236669	1993-08-17	Simmons et al.			

8	5237824	1993-08-24	Pawliszyn
9	5240390	1993-08-31	Kvinge et al.
10	5243821	1993-09-14	Schuck et al.
11	5246500	1993-09-21	Samata et al.
12	5251776	1993-10-12	Morgan Jr. et al.
13	5267455	1993-12-07	Deweese et al.
14	5280693	1994-01-25	Heudecker
15	5285352	1994-02-08	Pastore et al.
16	5288333	1994-02-22	Tanaka et al.
17	5313965	1994-05-24	Palen
18	5314574	1994-05-24	Takahashi
19	5328722	1994-07-12	Ghanayem et al.
20	5337446	1994-08-16	Smith et al.
21	5339844	1994-08-23	Stanford Jr. et al.
22	5355901	1994-10-18	Mielnik et al.
23	5368171	1994-11-29	Jackson
24	5370741	1994-12-06	Bergman
25	5377705	1995-01-03	Smith, Jr. et al.
26	5401322	1995-03-28	Marshall
27	5404894	1995-04-11	Shirahwa
28	5412958	1995-05-09	Iliff et al.
29	5417768	1995-05-23	Smith, Jr. et al.
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31	5447294	1995-09-05	Sakata et al.
32	5503176	1996-04-02	Dunmire et al.
33	5505219	1996-04-09	Lansberry et al.
34	5509431	1996-04-23	Smith, Jr. et al.
35	5526834	1996-06-18	Mielnik et al.
36	5533538	1996-07-09	Marshall
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38	5589224	1996-12-31	Tepman et al.
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	40	5629918	1997-05-13	Ho et al.
	41	5644855	1997-07-08	McDermott et al.
	42	5649809	1997-07-22	Stapelfeldt
	43	5656097	1997-08-12	Olesen et al.
	44	5669251	1997-09-23	Townsend et al.
	45	5702228	1997-12-30	Tamai et al.
	46	5706319	1998-01-06	Holtz
	47	5746008	1998-05-05	Yamashita et al.
	48	5797719	1998-08-25	James et al.
	49	5798126	1998-08-25	Fujikawa et al.
	50	5881577	1999-03-16	Sauer et al.

Remarks

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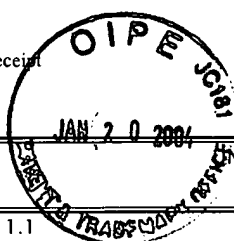
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Signature

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ACKNOWLEDGEMENT RECEIPT

Electronic Version 1.1

Stylesheet Version v1.1.1

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER									
Submission Type:	Information Disclosure Statement									
Application Number:	10/680783	*10/680783*								
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Application Number:	10/680783	*10/680783*	
Date:	2003-10-06		
First Named Applicant:	William Dale Jones		
Confirmation Number:	5859		
Attorney Docket Number:			
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>			
Submitted by:		Elec. Sign.	Sign. Capacity
Thomas B. Haverstock		/tbh/	Attorney
Registered Number: 32571			

Documents being submitted	Files
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Comments	

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

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Confirmation Number:	5859						
First Named Applicant:	William Jones						
Attorney Docket Number:							
Search string:	(5882165 or 5888050 or 5898727 or 5900107 or 5904737 or 5928389 or 5932100 or 5934856 or 5934991 or 5979306 or 5980648 or 5981399 or 5989342 or 6005226 or 6017820 or 6029371 or 6035871 or 6037277 or 6053348 or 6056008 or 6067728 or 6077053 or 6077321 or 6082150 or 6085935 or 6097015 or 6128830 or 6145519 or 6159295 or 6164297 or 6186722 or 6203582 or 6216364 or 6228563 or 6235634 or 6239038 or 6241825 or 6251250 or 6244121 or 6277753 or 6286231 or 6305677 or 6334266 or 6344174 or 6388317 or 6389677 or 6418956 or 6436824 or 6454945 or 6464790).pn.						
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
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	1	5882165	1999-03-16	Maydan et al.			
	2	5888050	1999-03-30	Fitzgerald et al.			
	3	5898727	1999-04-27	Fujikawa et al.			
	4	5900107	1999-05-04	Murphy et al.			
	5	5904737	1999-05-18	Preston et al.			
	6	5928389	1999-07-27	Jevtic			
	7	5932100	1999-08-03	Yager et al.			

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9	5934991	1999-08-10	Rush	
10	5979306	1999-11-09	Fujikawa et al.	
11	5980648	1999-11-09	Adler	
12	5981399	1999-11-09	Kawamura et al.	
13	5989342	1999-11-23	Ikedo et al.	
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15	6017820	2000-01-25	Ting et al.	
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18	6037277	2000-03-14	Masakara et al.	
19	6053348	2000-04-25	Morch	
20	6056008	2000-05-02	Adams et al.	
21	6067728	2000-05-30	Farmer et al.	
22	6077053	2000-06-20	Fujikawa et al.	
23	6077321	2000-06-20	Adachi et al.	
24	6082150	2000-07-04	Stucker	
25	6085935	2000-07-11	Malchow et al.	
26	6097015	2000-08-01	McCullough et al.	
27	6128830	2000-10-10	Bettcher et al.	
28	6145519	2000-11-14	Konishi et al.	
29	6159295	2000-12-12	Maskara et al.	
30	6164297	2000-12-26	Kamikawa	
31	6186722	2001-02-13	Shiral	B1
32	6203582	2001-03-20	Berner et al.	B1
33	6216364	2001-04-17	Tanaka et al.	B1
34	6228563	2001-05-08	Starov et al.	B1
35	6235634	2001-05-22	White et al.	B1
36	6239038	2001-05-29	Wen	B1
37	6241825	2001-06-05	Wytman	B1
38	6251250	2001-06-26	Keigler	B1
39	6244121	2001-06-12	Hunter	B1

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43	6334266	2002-01-01	Moritz et al.	B1
44	6344174	2002-02-05	Miller et al.	B1
45	6388317	2002-05-14	Reese	B1
46	6389677	2002-05-21	Lenz	B1
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Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal. The current electronic filing contains part 3 out of a total of 4 electronic filings.

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